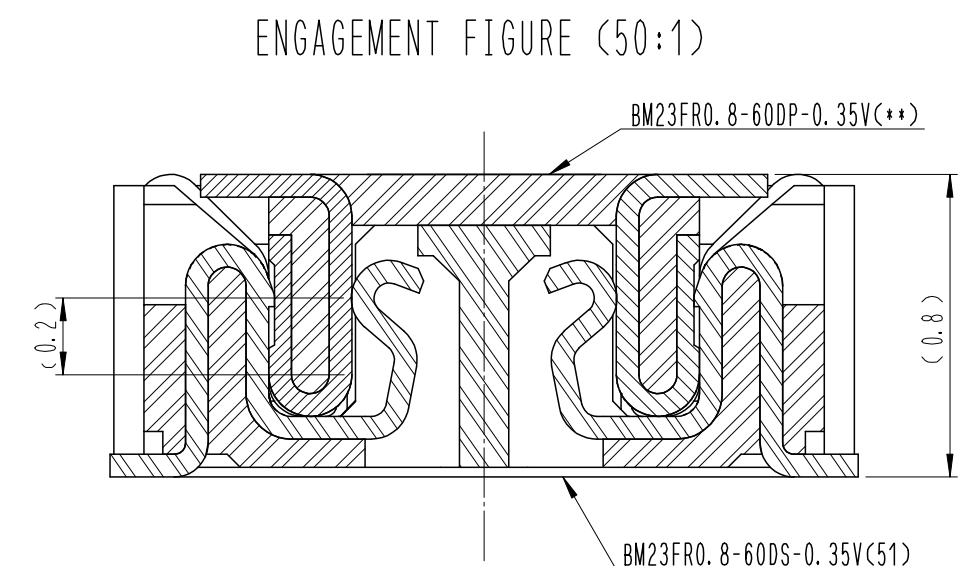
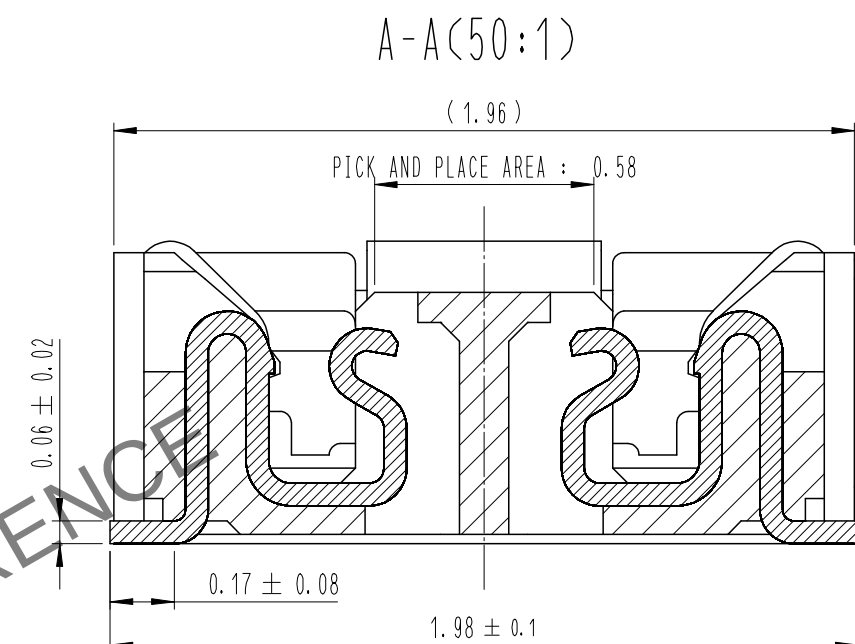
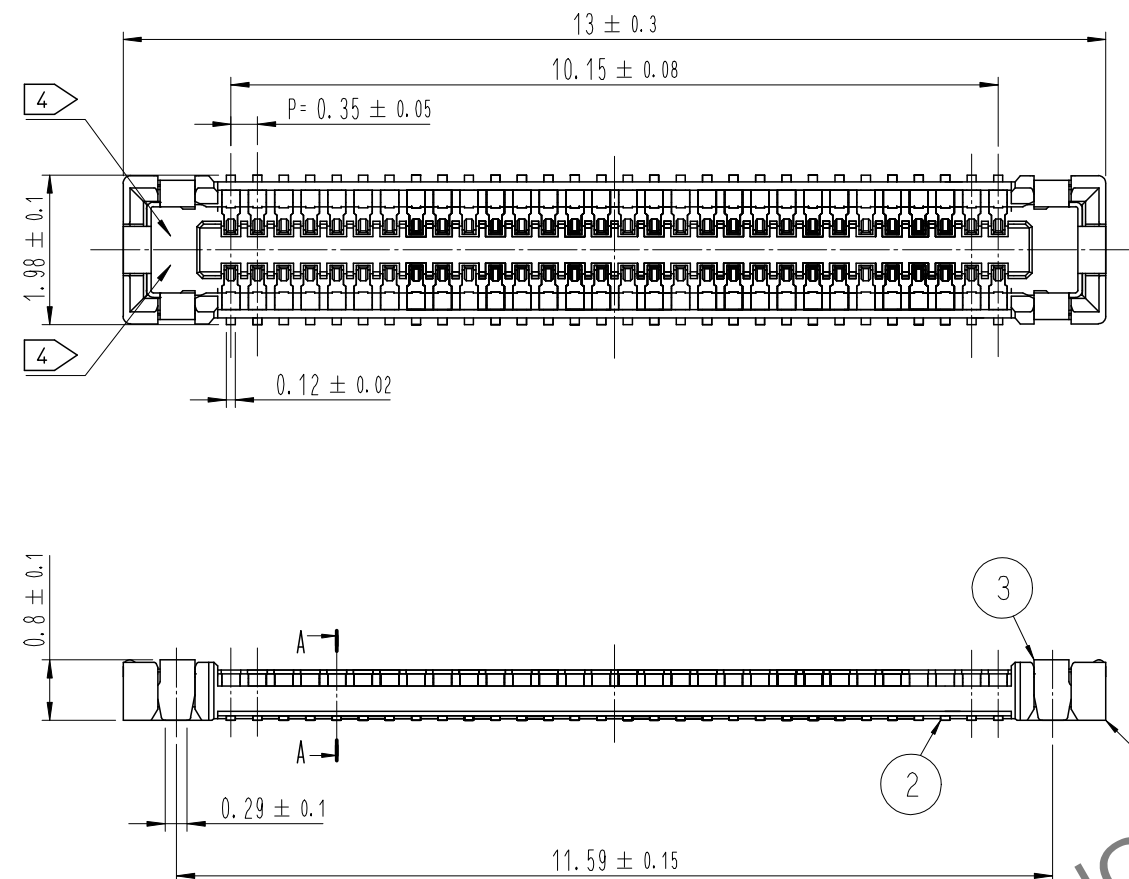
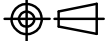


	COUNT	DESCRIPTION OF REVISIONS	B Y	CHKD	DATE		COUNT	DESCRIPTION OF REVISIONS	B Y	CHKD	DATE
①	1	Change the bobbin size	LYJ	JHW	15. 12. 03	△					. .
△					. .	△					. .
△					. .	△					. .



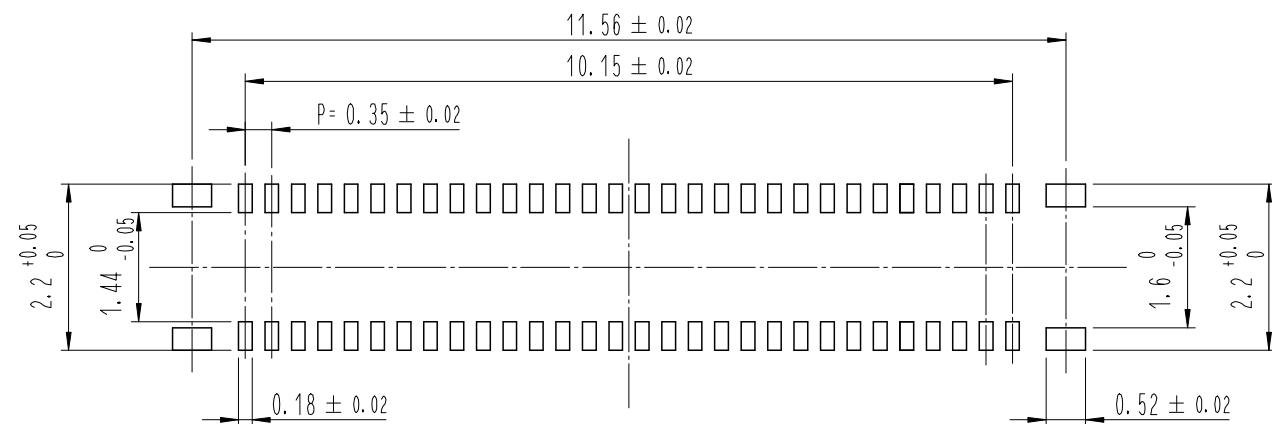
NOTE

1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX.
2. CONTACT PLATING SPECIFICATIONS.
CONTACT AREA : GOLD 0.05 μ m MIN.
SMT LEAD : GOLD 0.05 μ m MIN.
UNDERPLATING : NICKEL 1 μ m MIN.
(SURFACE : SEALING)
3. MATAL FITTING PLATING SPECIFICATIONS.
SMT LEAD : GOLD 0.05 μ m MIN.
UNDERPLATING : NICKEL 1 μ m MIN.
(SURFACE : SEALING)
4. HRS MARK AND CAV NO. IS INDICATED IN APPROX POSITION SHOWN.

4	PS	CLEAR (EMBOSSED CARRIER TAPE)			
3	PHOSPHOR BRONZE				
2	PHOSPHOR BRONZE		6	PS	BLACK (PLASTIC REEL)
1	LCP	UL94 V-0, BLACK	5	POLYESTER	CLEAR (COVER TAPE)
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
REMARKS				DRAWN Y. J. LEE 15. 12. 03	DESIGNED Y. J. LEE 15. 12. 03
				CHECKED H. W. JO 15. 12. 03	APPROVED T. S. KANG 15. 12. 03
				RELEASED 15. 12. 03	
CODE NO. (OLD)		DRAWING NO.	PART NO.		
	SCALE 10:1	EDC3-632085	BM23FR0.8-60DS-0.35V(51)		
	UNITS mm	 HIROSE KOREA CO., LTD.	CODE NO		CL 6644-0028-3-051
					1 3

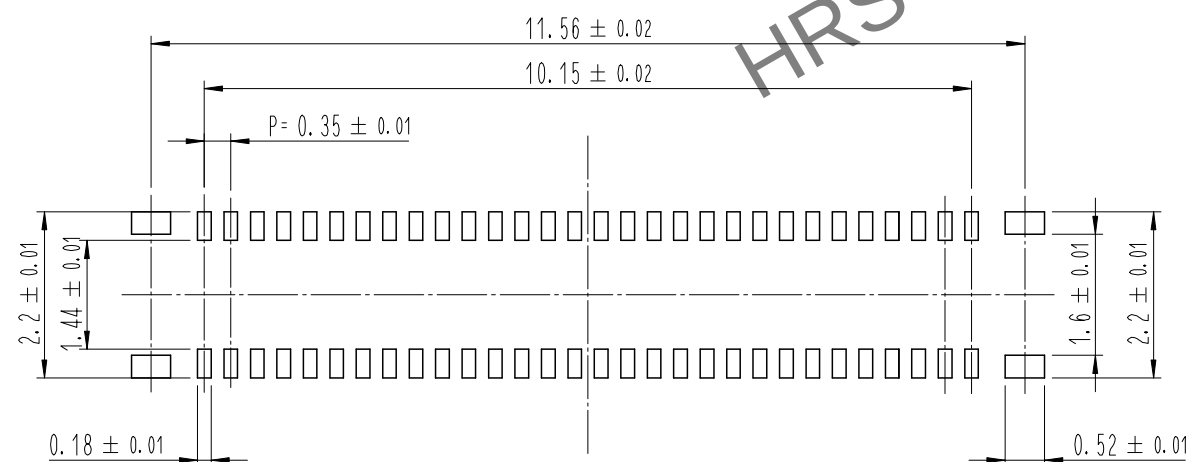
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6 RECOMMENDED PCB LAYOUT

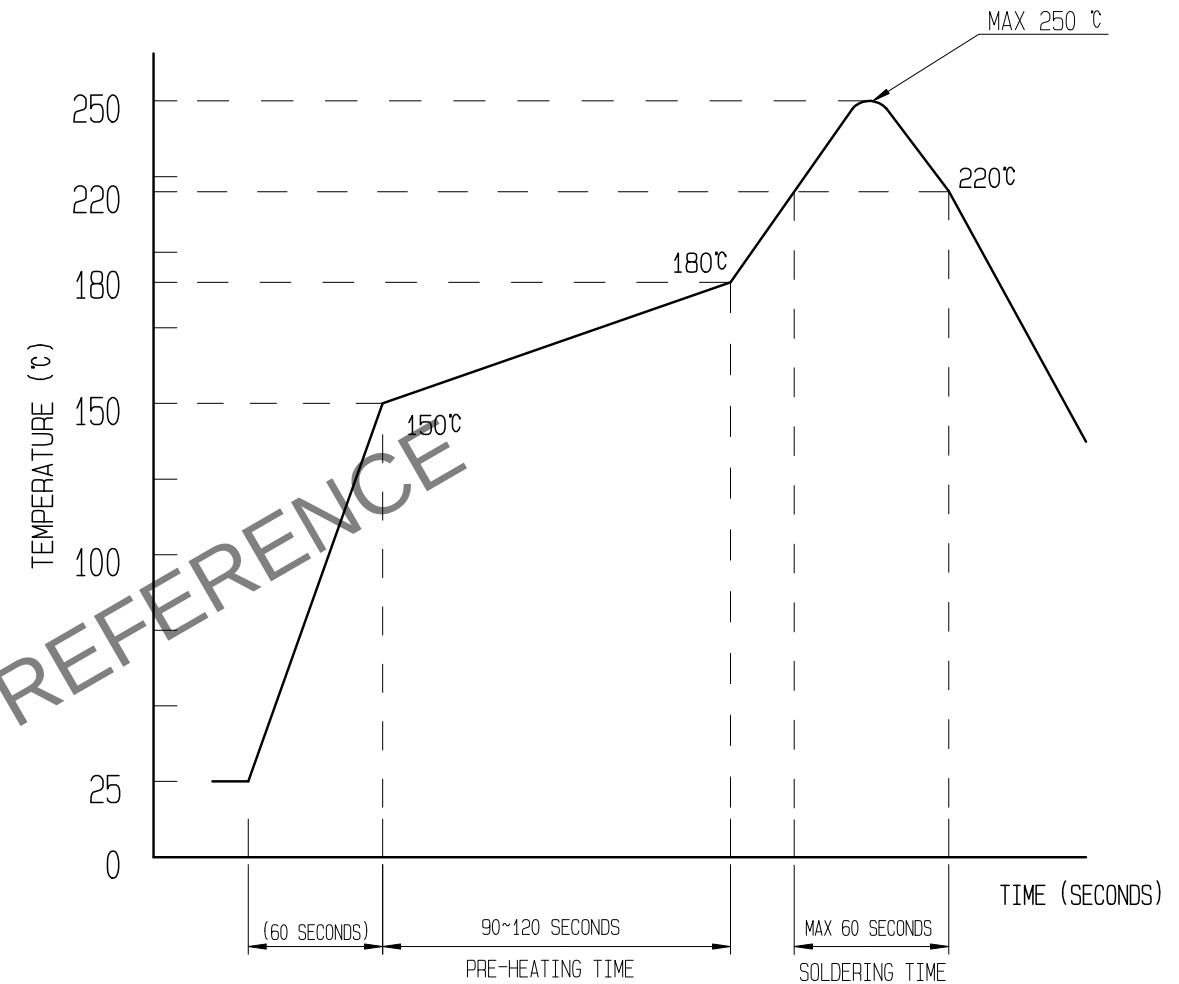


RECOMMENDED METAL MASK DIMENSIONS

MATAL MASK THICKNESS : $100 \mu\text{m}$



5 RECOMMENDED REFLOW TEMPERATURE PROFILE
USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD:IR REFLOW

NUMBER OF REFLOW CYCLES:2 CYCLES MAX.

1)REFLOW TIME

DURATION ABOVE 220 $^{\circ}\text{C}$. 60 SEC MAX.

(PEAK TEMPERATURE:250 $^{\circ}\text{C}$ MAX)

2)PRE-HEAT TIME

PRE-HEAT TEMPERATURE(MIN):150 $^{\circ}\text{C}$

PRE-HEAT TEMPERATURE(MAX):180 $^{\circ}\text{C}$

PRE-HEAT TIME:90-120 SEC.

5. THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE.
ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND
OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE,
A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED
PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.
6. PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

	DRAWING NO.	EDC3-632085	PART NO.	BM23FR0.8-60DS-0.35V(51)	
	SCALE	10:1	CODE NO	CL 6644-0028-3-051	2/3
	UNITS	mm	HIROSE KOREA CO., LTD.		

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